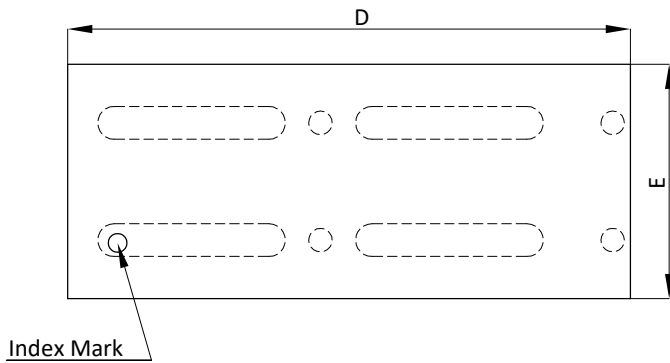
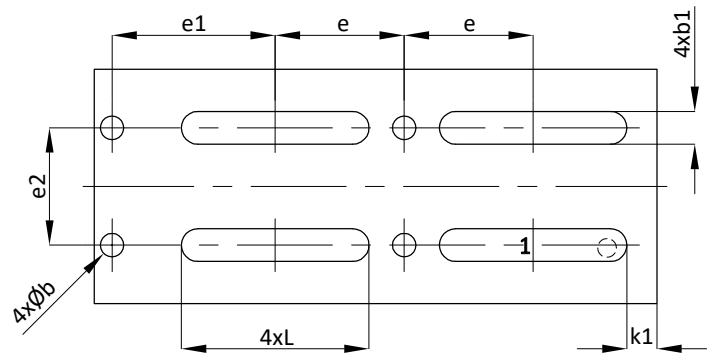




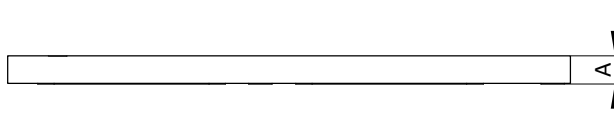
RigidCSP6x2.5_8 PACKAGE OUTLINE



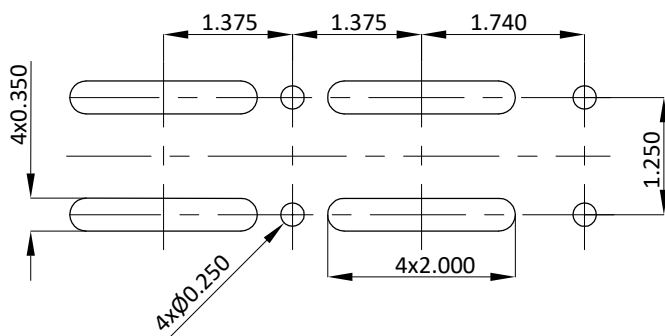
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN

SYMBOLS	DIM. IN MM			DIM. IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.270	0.300	0.330	---	0.012	0.013
b	0.220	0.250	0.280	0.009	0.010	0.011
b1	0.320	0.350	0.380	0.013	0.014	0.015
D	5.970	6.000	6.030	0.235	0.236	0.237
E	2.470	2.500	2.530	0.097	0.098	0.100
e	1.375BSC.			0.054BSC.		
e1	1.740BSC.			0.069BSC.		
e2	1.250BSC.			0.049BSC.		
K1	----	0.320	----	----	0.013	----
L	1.970	2.000	2.030	0.078	0.079	0.080

NOTE:

1. CONTROLLED DIMENSIONS ARE IN MILLIMETERS.
2. TOP VIEW IS THE VIEW OF TOP SURFACE OF THE PART HAVING INDEX AND PART NUMBER MARKING.
3. CHIPPING ON SIDE WALL CAN'T BE EXCEED 2/3 DUMMY DIE THICKNESS FROM DIE BACKSIDE. CHIPPING ON BACKSIDE NEED FOLLOW WIDTH < 100UM, LENGTH < 1/3 DIE SIZE (ACCUMULATIVE LENGTH MEASURED AT WIDTH > 50UM).
4. THIS PACKAGE WAS QUALIFIED USING IR REFLOW PROCESS (JEDEC STANDARD). FOR USAGE IN OTHER SOLDERING PROCESSES, PLEASE CONTACT LOCAL AOS REPRESENTATIVES.